Table (CKTS / DIM. A / DIM. B):

CKTS	DIM. A	DIM. B
04	(5.08)/.200	(2.54)/.100
06	(7.62)/.300	(5.08)/.200
08	(10.16)/.400	(7.62)/.300
10	(12.70)/.500	(10.16)/.400
12	(15.24)/.600	(12.70)/.500
14	(17.78)/.700	(15.24)/.600
16	(20.32)/.800	(17.78)/.700
18	(22.36)/.900	(20.32)/.800
20	(25.40)/1.000	(22.36)/.900
22	(27.94)/1.100	(25.40)/1.000
24	(30.48)/1.200	(27.94)/1.100
26	(33.02)/1.300	(30.48)/1.200
28	(35.56)/1.400	(33.02)/1.300
30	(38.10)/1.500	(35.56)/1.400

2.54 ±0.05 TYP. .100 ±.002 (NON-ACCUM.)

2.54 ±0.05 .100 ±.002

(2.29) .090 REF.

BANDOLIER PIN (0.64)/.025 SQUARE

Ø 1.14 ±0.05 .045 ±.002 TYP.

RECOMMENDED P.C. BOARD HOLE LAYOUT

DIM. A REF.
DIM. B REF.
(1.27) .050 REF.
CKT. 3
CKT. 5
CKT. 7
CKT. 1

C ± (0.25) .010
(2.54) .100 SEE NOTE 8

(5.08) .200 REF.

(2.54) .100

(1.27) .050 REF.

CKT. 8
CKT. 6
CKT. 2
CKT. 4

(2.54) .100 TYP.

E REF.

(2.29) .090 REF.

(1.27) .050 SEE NOTE 8

(2.54) .100 REF.

NOTES:
1. MATERIAL: WAFER – HIGH TEMPERAURE THERMAL PLASTIC, 94V-0; COLOR: BLACK
   PIN – COPPER ALLOY
2. PLATING:
   TIN – (0.00381)/.000150 MINIMUM TIN PLATE
        OVER NICKEL PLATE.
   15 GOLD – (0.00038)/.000015 MINIMUM GOLD PLATE IN SELECT AREA,
        (0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA,
        OVER NICKEL PLATE OVERALL.
   30 GOLD – (0.00076)/.000030 MINIMUM GOLD PLATE IN SELECT AREA,
        (0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA,
        OVER NICKEL PLATE OVERALL.
* THE PRIMARY SHPPING CARTON WILL BE LABELD 'COMPLIANT TO
   RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC'.
   CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.
3. PRODUCT CONFORMS TO PS-71764.
4. PACKAGING INFORMATION:
   FOR 4 THRU 8 CIRCUIT PARTS USE PK-70873-0353
   FOR 10 CIRCUITS AND OVER USE PK-70873-0075
5. FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
6. PINS MUST MEET SOLDERABILITY SPEC. ES-152, EXCEPT VOIDS ARE
   PERMISSIBLE AT BANDOLIER PIN AT BANDOLIER PIN FAYING SURFACE.
   (APPROX. (0.64)/.025 LNG X (0.15)/.006 WD. REF.) 2 LOCATIONS
7. WAFER TO BE FLAT WITHIN (0.03 MM/CM) OR .003 IN./IN
8. MEASURE POINT FOR PLATING THICKNESS.
9. THIS PART CONFORMS TO CLASS B REQUIREMENTS
   OF COSMETIC SPECIFICATION PS-45499-002

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	±.01
2 PLACES	± 0.25	±.01
1 PLACE	± 0.25	± ---
ANGULAR ±1/2°		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY: CAC   DATE: 1995/08/23
CHECKED BY: PR   DATE: 1995/08/23
APPROVED BY: DJB   DATE: 1995/08/23

TITLE:
DUAL ROW WAFER ASS'Y
W/BREAK-OFF OPTION RT.
ANG. (0.64)/.025 SQ PINS

MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-71764-001
SHEET NO.: 1 OF *
SIZE: C

	2	A
	1	A1
	SHT.	REV.

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

tb_frame_C_P_ME_T Rev. E 2006/04/15

ITEM NO: 71764-0004/0030, 9003		
DIM. C		(6.10)/.240
DIM. E (REF.)		(2.79)/.110
FINISH		TIN
CONNECTOR END PLATING		TIN
P.C. BOARD END PLATING		TIN
PACKAGING		SEE NOTE 4 SHEET 1
CKTS	ITEM NUMBER	VOIDS
04	71764-0004	
06	71764-0006	
08	71764-0008	
10	71764-0010	
12	71764-0012	
14	71764-0014	
16	71764-0016	
18	71764-0018	
20	71764-0020	
22	71764-0022	
24	71764-0024	
26	71764-0026	
28	71764-0028	
30	71764-0030	
06	71764-9003	3

ITEM NO: 71764-0104/0130, 9001, 9004		
DIM. C		(6.10)/.240
DIM. E (REF.)		(2.79)/.110
FINISH		15 GOLD
CONNECTOR END PLATING		GOLD
P.C. BOARD END PLATING		TIN
PACKAGING		SEE NOTE 4 SHEET 1
CKTS	ITEM NUMBER	VOIDS
04	71764-0104	
06	71764-0106	
08	71764-0108	
10	71764-0110	
12	71764-0112	
14	71764-0114	
16	71764-0116	
18	71764-0118	
20	71764-0120	
22	71764-0122	
24	71764-0124	
26	71764-0126	
28	71764-0128	
30	71764-0130	
06	71764-9001	3, 4
08	71764-9004	5, 6

ITEM NO: 71764-0204/0230, 9000, 9002		
DIM. C		(6.10)/.240
DIM. E (REF.)		(2.79)/.110
PLATING FINISH		30 GOLD
CONNECTOR END PLATING		GOLD
P.C. BOARD END PLATING		TIN
PACKAGING		SEE NOTE 4 SHEET 1
CKTS	ITEM NUMBER	VOIDS
04	71764-0204	
06	71764-0206	
08	71764-0208	
10	71764-0210	
12	71764-0212	
14	71764-0214	
16	71764-0216	
18	71764-0218	
20	71764-0220	
22	71764-0222	
24	71764-0224	
26	71764-0226	
28	71764-0228	
30	71764-0230	
06	71764-9002	3, 4
10	71764-9000	8

REV: **A**	ECR/ECN INFORMATION EC No: **UCP2007-0449** DATE: **2006-08-18**	TITLE: **DUAL ROW WAFER ASS'Y W/ BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS**	SHEET No. **- 2 -**
DOCUMENT NUMBER: **SD-71764-001**	CREATED / REVISED BY: **PRIDDER**	CHECKED BY: **ADERR**	APPROVED BY: **FSMITH**

ITEM NO: 71764-0304/0330		
DIM. C		(8.13)/.320
DIM. E (REF.)		(2.79)/.110
PLATING FINISH		TIN
CONNECTOR END PLATING		TIN
P.C. BOARD END PLATING		TIN
PACKAGING		SEE NOTE 4 SHEET 1
CKTS	ITEM NUMBER	VOIDS
04	71764-0304	
06	71764-0306	
08	71764-0308	
10	71764-0310	
12	71764-0312	
14	71764-0314	
16	71764-0316	
18	71764-0318	
20	71764-0320	
22	71764-0322	
24	71764-0324	
26	71764-0326	
28	71764-0328	
30	71764-0330	

ITEM NO: 71764-0404/0430		
DIM. C		(8.13)/.320
DIM. E (REF.)		(2.79)/.110
PLATING FINISH		15 GOLD
CONNECTOR END PLATING		GOLD
P.C. BOARD END PLATING		TIN
PACKAGING		SEE NOTE 4 SHEET 1
CKTS	ITEM NUMBER	VOIDS
04	71764-0404	
06	71764-0406	
08	71764-0408	
10	71764-0410	
12	71764-0412	
14	71764-0414	
16	71764-0416	
18	71764-0418	
20	71764-0420	
22	71764-0422	
24	71764-0424	
26	71764-0426	
28	71764-0428	
30	71764-0430	

ITEM NO: 71764-0504/0530		
DIM. C		(8.13)/.320
DIM. E (REF.)		(2.79)/.110
PLATING FINISH		30 GOLD
CONNECTOR END PLATING		GOLD
P.C. BOARD END PLATING		TIN
PACKAGING		SEE NOTE 4 SHEET 1
CKTS	ITEM NUMBER	VOIDS
04	71764-0504	
06	71764-0506	
08	71764-0508	
10	71764-0510	
12	71764-0512	
14	71764-0514	
16	71764-0516	
18	71764-0518	
20	71764-0520	
22	71764-0522	
24	71764-0524	
26	71764-0526	
28	71764-0528	
30	71764-0530	

REV: **A**	ECR/ECN INFORMATION EC No: **UCP2007-0449** DATE: **2006-08-18**	TITLE: DUAL ROW WAFER ASS'Y W/ BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS	SHEET No. **- 3 -**
DOCUMENT NUMBER: **SD-71764-001**	CREATED / REVISED BY: **PRIDDER**	CHECKED BY: **ADERR**	APPROVED BY: **FSMITH**